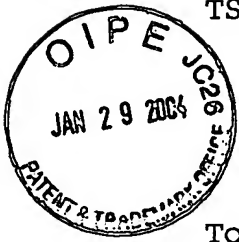TSMC-02-1033

January 13, 2004

To: Commissioner for Patents
P.O.Box 1450
Alexandria, VA 22313-1450

Fr: George O. Saile, Reg. No. 19,572
28 Davis Avenue
Poughkeepsie, N.Y. 12603

Subject:

| Serial No.   10/696,006   10/29/03 |

Kuo-Chi Tu

STRUCTURE FOR REDUCING LEAKAGE
CURRENTS AND HIGH CONTACT RESISTANCE
FOR EMBEDDED MEMORY AND METHOD FOR
MAKING SAME

INFORMATION DISCLOSURE STATEMENT

Enclosed is Form PTO-1449, Information Disclosure Citation

In An Application.

The following Patents and/or Publications are submitted to

comply with the duty of disclosure under CFR 1.97-1.99 and

37 CFR 1.56.

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being
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P.O. Box 1450, Alexandria, VA 22313-1450, on January 27, 2004.

Stephen B. Ackerman, Reg.# 37761

Signature/Date _____ 1/27/04

1

U.S. Patent 6,403,417 to Chien et al., "Method for In-situ Fabrication of a Landing Via and a Strip Contact in an Embedded Memory," describes a method for making via holes and strip contact holes for embedded memory.

U.S. Patent 6,485,988 to Ma et al., "Hydrogen-free Contact Etch for Ferroelectric Capacitor Formation," describes a method for using a hydrogen-free contact etch for ferroelectric capacitor formation.

Sincerely

Stephen B. Ackerman,
Reg. No. 37761

Form PTO-1449

INFORMATION DISCLOSURE CITATION IN AN APPLICATION

(Use several sheets if necessary)

Docket Number (Optional)	Application Number
TSMC-02-1033	10/696,006

Applicant
Kuo-Chi Tu

Filing Date	Group Art Unit
10/29/03	

U. S. PATENT DOCUMENTS

EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
	6 4 0 3 4 1 7	6/11/02	Chien et al.	438	241	3/13/01
	6 4 8 5 9 8 8	11/26/02	Ma et al.	438	3	12/19/00

FOREIGN PATENT DOCUMENTS

	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	Translation YES	NO

OTHER DOCUMENTS *(Including Author, Title, Date, Pertinent Pages, Etc.)*

EXAMINER	DATE CONSIDERED

EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP § 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to the applicant.

OIPE JC26
JAN 29 2004
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